

Filename: PMP7130RevC - BoM.xls

Date: 4/10/2012

PMP7130RevC - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	100uF	Capacitor, Aluminum, 63V, 20%	0.406 x 0.457 inch	63CV100KX	Sanyo
1	C10	180uF	Capacitor, Aluminum, 16V, 20mOhm, 3.6A, 20%	Code D8	16SVP180M	Sanyo
1	C11	open	Capacitor, Aluminum, 16V, 20mOhm, 3.6A, 20%	Code D8	EEEFKxyyAP	Panasonic
1	C12	open	Capacitor, Ceramic, 25V, X5R, 10%	1210	Std	Std
2	C2, C3	4.7uF	Capacitor, Ceramic, 50V, X7R, 15%	1210	Std	Std
1	C4	1uF	Capacitor, Ceramic, 16V, X7R, 15%	603	Std	Std
1	C5	680pF	Capacitor, Ceramic, 50V, X7R, 15%	603	Std	Std
1	C6	100pF	Capacitor, Ceramic, 50V, X7R, 15%	603	Std	Std
1	C7	1uF	Capacitor, Ceramic, 16V, X7R, 15%	805	Std	Std
1	C8	1uF	Capacitor, Ceramic, 50V, X7R, 15%	1206	Std	Std
1	C9	10uF	Capacitor, Ceramic, 16V, X7R, 15%	1210	Std	Std
1	D2	MBRD360	Diode, Schottky, 60V, 3A	DPAK	MBRD360	ON Semi
1	J1	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	L1	15uH	Inductor, SMT, 72mOhm, 9.1A sat, 2.3A rms	0.484 x 0.484 inch	MSD1278 -153ML	Coilcraft
2	P1, P3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	P2, P4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	Q1	SQ4850EY	MOSFET, Nch, 60V, 8.5A, 22milliohm	SO8	SQ4850EY	Vishay
2	R1, R9	1.00k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R10	75.0k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R101	49.9	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R2, R5	20.0k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R3	12.1k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R6	102k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R7	open	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R8	20m	Resistor, Chip, 1/2W, 1%	1210	Std	Std
1	SW	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP3	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	LM3481	IC, High Efficiency Low-Side N-Channel Controller	MSOP	LM3481MM	Texas Instruments

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